

Schedule of Special Topic Courses for the M.Eng. Program in Microelectronics Packaging (Two Year Planner)

Fall 2005	
MSE 498/598	Microelectronics Packaging
EEE 498/598	Overview of Electrical Engineering
IEE 498/598	Designed Experiments, Statistical Process Control and Statistical Reasoning for Semiconductor Processing and Microelectronics Packaging
MAE 498/598	Overview of Mechanical Engineering
MSE 498/598	Overview of Materials Engineering

Spring 2006	
EEE 691	Advanced Packaging Analysis and Design: Electrical Considerations
IEE 691	Advanced Analysis Methods
MAE 498/598	Heat Transfer
MAE 691	Advanced Packaging Analysis and Design: Mechanical Considerations
MSE 691	Advanced Packaging Analysis and Design: Material Considerations

Fall 2006	
MSE 498/598	Microelectronics Packaging
EEE 498/598	Overview of Electrical Engineering
IEE 498/598	Designed Experiments, Statistical Process Control and Statistical Reasoning for Semiconductor Processing and Microelectronics Packaging
MAE 498/598	Overview of Mechanical Engineering
MSE 498/598	Overview of Materials Engineering

Spring 2007	
EEE 691	Advanced Packaging Analysis and Design: Electrical Considerations
IEE 691	Advanced Analysis Methods
MAE 498/598	Heat Transfer
MAE 691	Advanced Thermal Packaging
MSE 691	Advanced Packaging Analysis and Design: Material Considerations